



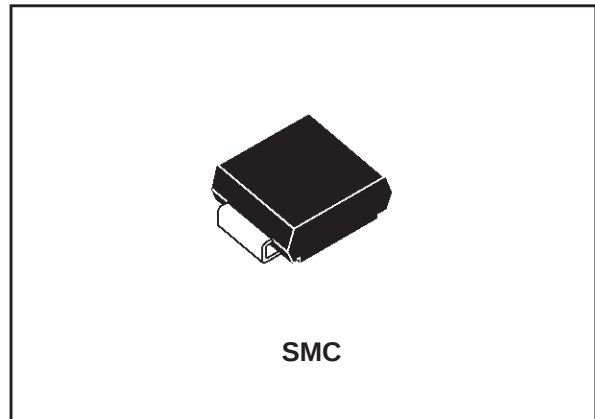
SMTHDTxx

Application Specific Discretes
A.S.D.TM

TRISILTM
DISCRETE SOLUTION FOR ISDN PROTECTION

FEATURES

- UNIDIRECTIONAL CROWBAR PROTECTION.
- PEAK PULSE CURRENT:
IPP = 75 A , 10/1000 μ s.
- HOLDING CURRENT = 150mA.
- BREAKDOWN VOLTAGE:
SMTHDT58 = 58V.
SMTHDT80 = 80V.
SMTHDT120 = 120V.
- PACKAGES:
SMTHDTxx = SURFACE MOUNT PACKAGE.



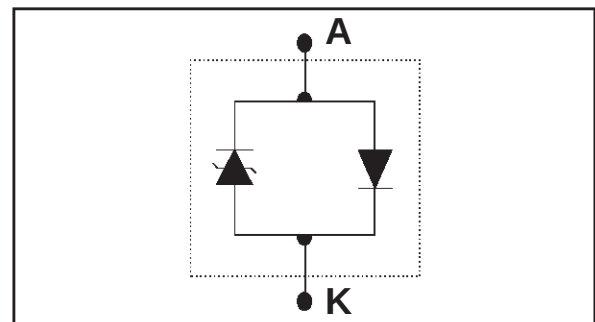
DESCRIPTION: TRIBALANCED PROTECTION

Dedicated protection devices for ISDN LINE CARD and high speed data telecom lines.

Used with the recommended configuration using 3 components, they will provide =

- Dual bidirectionnal protection, with fixed breakdown voltage in both common and differential modes.
- Low capacitances from lines to ground.
- Very good capacitance balance : $\Delta C = 30$ pF.

FUNCTIONAL DIAGRAM.



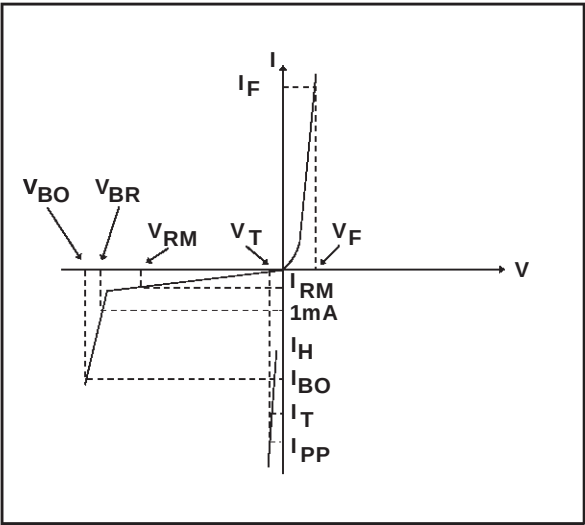
ABSOLUTE RATINGS (limiting values) ($-40^{\circ}\text{C} \leq T_{\text{amb}} \leq +85^{\circ}\text{C}$)

Symbol	Parameter		Value	Unit
IPP	Peak pulse current	10/1000 μ s 8/20 μ s	75 150	A
ITSM	Non repetitive surge peak on-state current	tp = 20 ms	30	A
di/dt	Critical rate of rise of on-state current	Non repetitive	100	A/ μ s
dv/dt	Critical rate of rise of off-state voltage	67% VBR	5	KV/ μ s
Tstg Tj	Storage and operating junction temperature range		- 40 to + 150 + 150	$^{\circ}\text{C}$ $^{\circ}\text{C}$

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
Rth (j-l)	Junction-leads Thermal Resistance	SMC	200	$^{\circ}\text{C}/\text{W}$

Symbol	Parameter
V_{RM}	Stand-off voltage
V_{BR}	Breakdown voltage
V_{BO}	Breakover voltage
I_H	Holding current
V_T	On-state voltage
V_F	Forward Voltage Drop
I_{BO}	Breakover current
I_{PP}	Peak pulse current
V_F	Forward Voltage Drop



PARAMETERS RELATED TO THE DIODE.

Parameter	Test conditions	Value	Unit
V_F	$I_F = 5A, T_P = 500 \mu s$	5	V

PARAMETERS RELATED TO THE PROTECTION TRISIL.

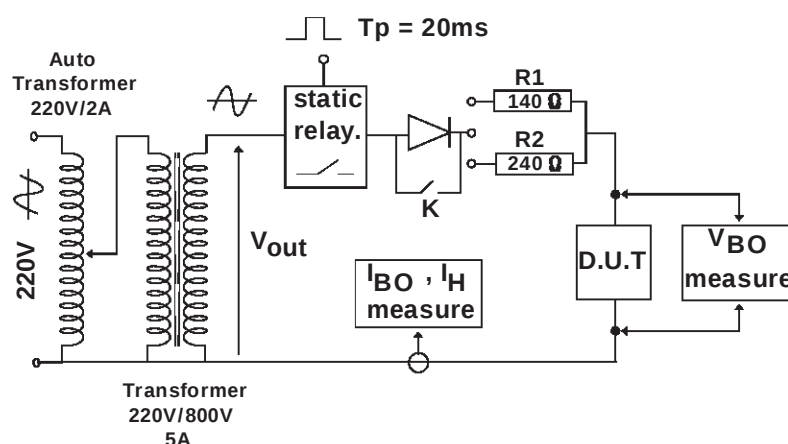
Types	$I_R @ V_{RM}$		$V_{BR} @ I_R$		V_{BO}	I_{BO}		I_H	V_T	C
	max		min		max	min	max	min	max	max
	μA	V	V	mA	V	note1	note1	note1	note2	note3
SMTHDT58	10	56	58	1	80	150	800	150	5	400
SMTHDT80	10	68	80	1	120	150	800	150	5	250
SMTHDT120	10	102	120	1	180	150	800	150	5	200

All parameters tested at 25 °C, except where indicated.

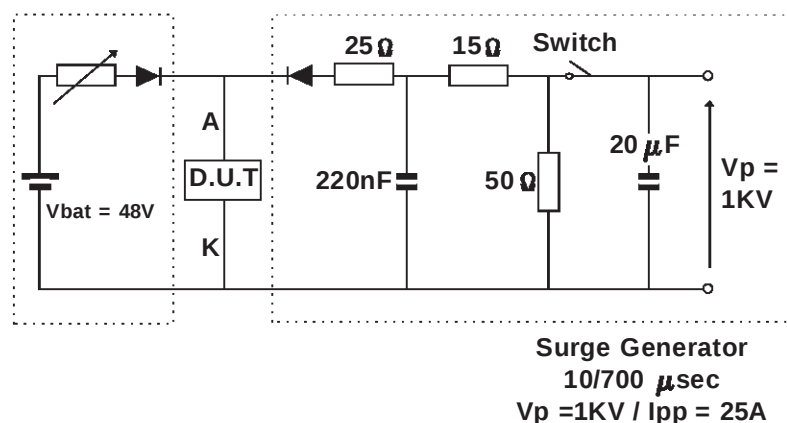
Note 1 : See the reference test circuit for I_H , I_{BO} and V_{BO} parameters.

Note 2 : Square pulse $T_p = 500 \mu s - I_T = 5A$.

Note 3 : $V_R = 1V, F = 1MHz$.

REFERENCE TEST CIRCUIT FOR I_H , I_{BO} and V_{BO} parameters :

TEST PROCEDURE :

- Pulse Test duration ($T_p = 20ms$):
 - For Bidirectional devices = Switch K is closed
 - For Unidirectional devices = Switch K is open.
- V_{OUT} Selection
 - Device with $V_{BR} \leq 150$ Volt
 - $V_{OUT} = 250 V_{RMS}$, $R_1 = 140 \Omega$.
 - Device with $V_{BR} \geq 150$ Volt
 - $V_{OUT} = 480 V_{RMS}$, $R_2 = 240 \Omega$.

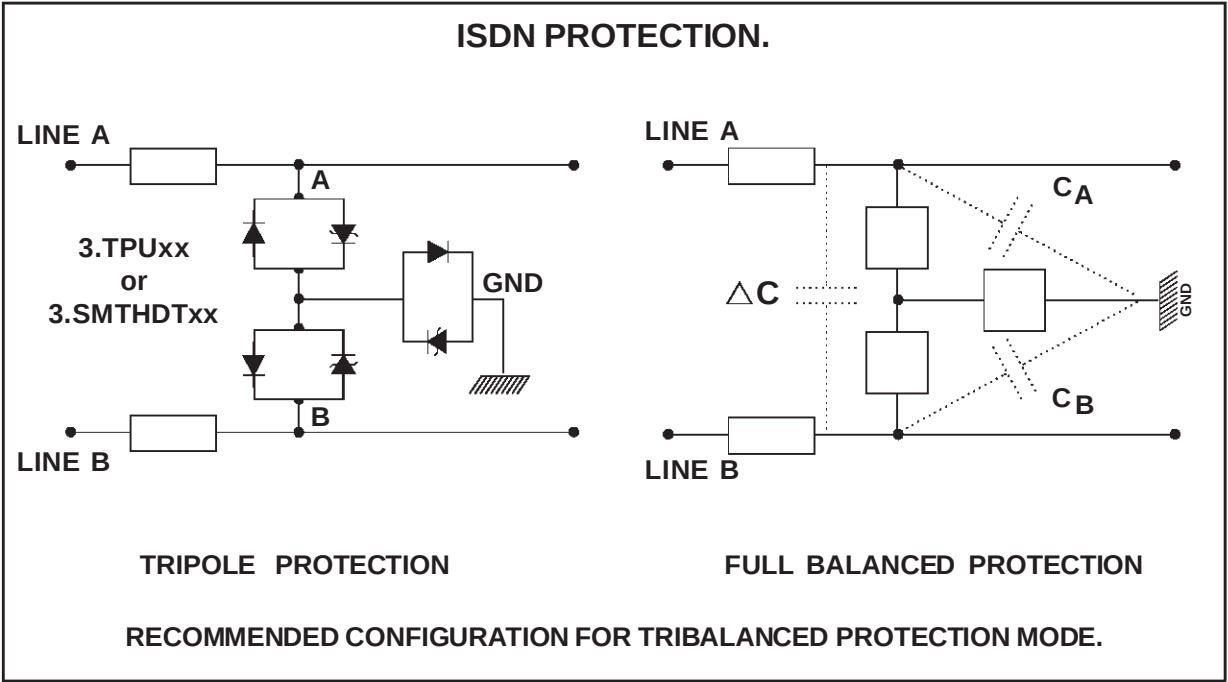
FUNCTIONAL HOLDING CURRENT (I_H) TEST CIRCUIT = GO - NOGO TEST.


This is a GO-NOGO Test which allows to confirm the holding current (I_H) level in a functional test circuit. This test can be performed if the reference test circuit can't be implemented.

TEST PROCEDURE :

- 1) Adjust the current level at the I_H value by short circuiting the AK of the D.U.T.
- 2) Fire the D.U.T with a surge Current : $I_{pp} = 25A$, $10/700 \mu s$.
- 3) The D.U.T will come back to the OFF-State within a duration of 50 ms max.

APPLICATION NOTE

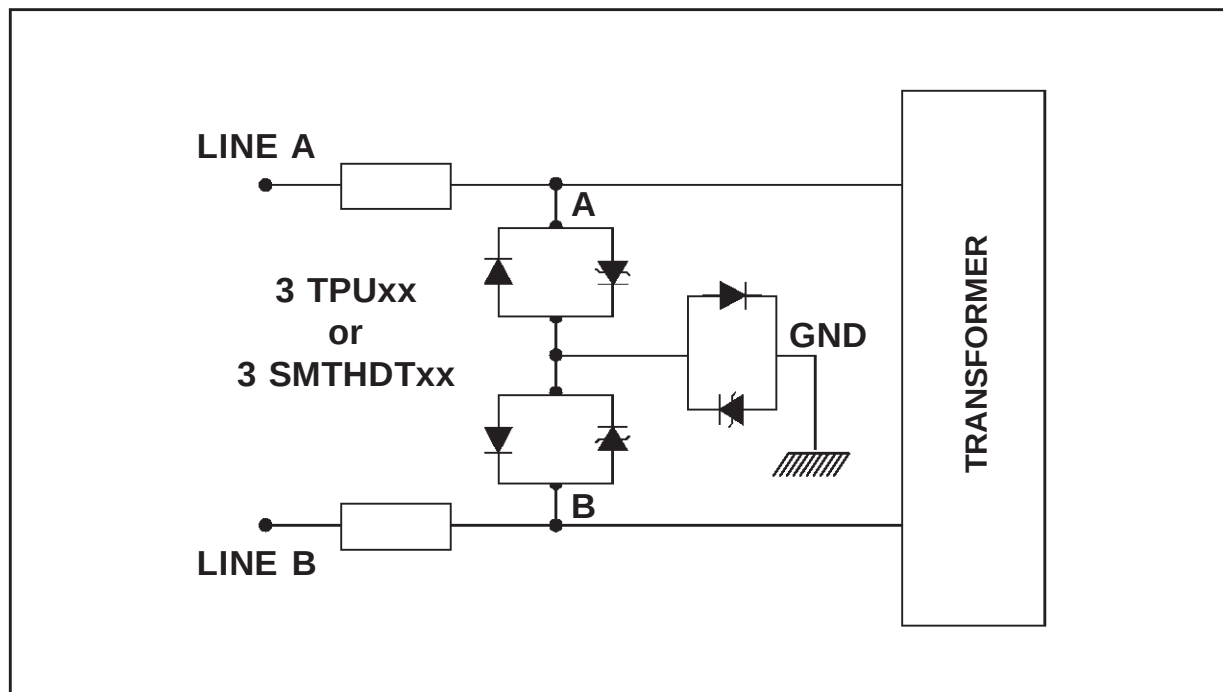


CAPACITANCE CHARACTERISTICS

Type	CONFIGURATION		C _A pF Max	C _B pF Max	ΔC pF Max
	LINE A	LINE B			
SMTHDT58	48	0	80	60	30
SMTHDT80	56	0	70	50	30
SMTHDT120	110	0	70	50	30

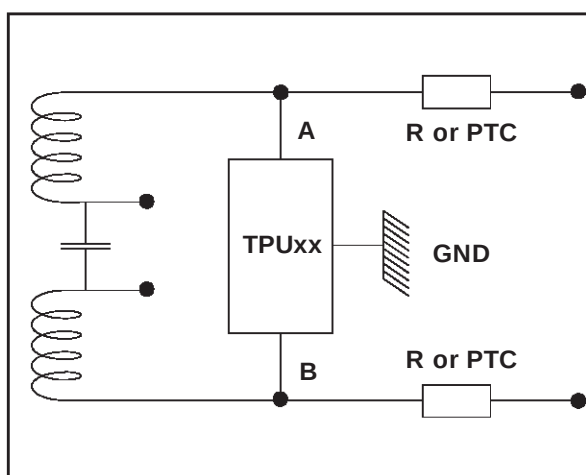
APPLICATION NOTE

Discrete ISDN Protection solution

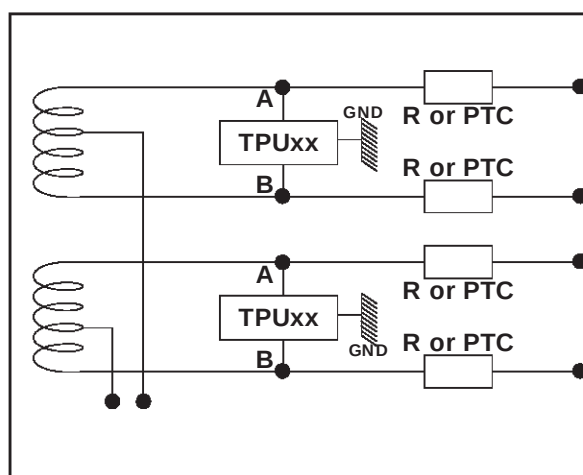


EQUIVALENT PROTECTION FUNCTION

U Interface Protection

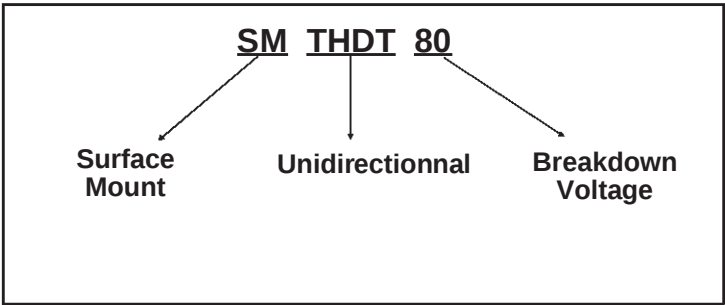


S Interface Protection



This topology assumes the same breakdown voltage level in positive and negative for differential or common mode surge.

ORDER CODE



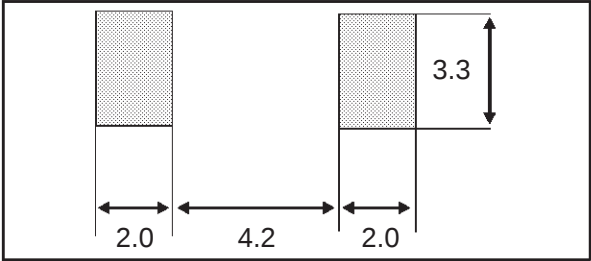
MARKING

Package	Type	Marking
SMC	SMTHDT58 SMTHDT80 SMTHDT120	W01 W03 W05

PACKAGE MECHANICAL DATA
SMC

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.2	0.114	0.126
c	0.15	0.41	0.006	0.016
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
D	5.55	6.25	0.218	0.246
L	0.75	1.60	0.030	0.063

FOOTPRINT DIMENSIONS (in millimeters)



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